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9 February 2024

Cookpad Inc.
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Non-Payment of Dividends Out of Surplus 2023

Cookpad Inc. (the “Company”) hereby announces that its Board of Directors today resolved not to pay dividends out of surplus on shares of the Company’s stock held as of 31 December 2023, as described below.

1. Detailed description of dividends

	Dividend for FY2023	Most recent forecast (announced on 11 Nov. 2023)	Dividend paid for FY2022 (ended 31 Dec. 2022)
Record date	31 December 2023	31 December 2023	31 December 2022
Dividend per share	0 yen	0 yen	0 yen
Total payment	-	-	-
Effective date	-	-	-
Source of dividends	-	-	-

2. Reasons for non-payment

To focus on building the foundation for further growth, the Company decided not to pay dividends, prioritising investment for business expansion through service development, user base boosting and better branding over other uses of profits earned from its business activities.